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(54) COAXIAL WAVEGUIDE MICROSTRUCTURE HAVING CONDUCTIVE AND INSULATION MATERIALS DEFINING VOIDS THEREIN

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

This patent is subject to a terminal dis-

claimer.

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Related U.S. Application Data

- (63) Continuation of application No. 11/637,629, filed on Dec. 12, 2006, now Pat. No. 7,405,638, which is a continuation of application No. 11/316,417, filed on Dec. 22, 2005, now Pat. No. 7,148,772, which is a continuation of application No. 10/793,574, filed on Mar. 4, 2004, now Pat. No. 7,012,489.
- (60) Provisional application No. 60/452,073, filed on Mar. 4, 2003, provisional application No. 60/474,549, filed on May 29, 2003.
- (51) **Int. Cl. H01P 3/06** (2006.01)

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(57) ABSTRACT

Provided are coaxial waveguide microstructures. The microstructures include a substrate and a coaxial waveguide disposed above the substrate. The coaxial waveguide includes: a center conductor; an outer conductor including one or more walls, spaced apart from and disposed around the center conductor; one or more dielectric support members for supporting the center conductor in contact with the center conductor and enclosed within the outer conductor; and a core volume between the center conductor and the outer conductor, wherein the core volume is under vacuum or in a gas state. Also provided are methods of forming coaxial waveguide microstructures by a sequential build process and hermetic packages which include a coaxial waveguide microstructure.

14 Claims, 18 Drawing Sheets

